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Jameco Part Number 1444560





1.0 SCOPE

This specification covers the performance requirements and test methods for the following products listed by series numbers:

REVISION:		110N: 111LE:	PRODUCT SPECIFICATION FOR	<u>SHEET NO.</u>
* 75	117		VHDM 8 Row Daughtercard Stacker	
* 75	286		VHDM L-Series 6 Row RAM Assembly	- J
* 75	165		VHDM 8 Row Right Angle Male (RAM) Asse	embly
* 74	600		VHDM 6 Row Right Angle Male (RAM) Asse	embly
* 75	299		VHDM / VHDM-HSD / VHDM-L 6 Row Dcar	d Tri-brid
* 75	298		VHDM-HSD / VHDM-L 8 Row Daughtercard	Hybrid
* 75	192		VHDM / VHDM-L 8 Row Daughtercard Hybr	id
* 75	191		VHDM L-Series 8 Row Daughtercard Assem	าbly
* 75	297		VHDM / VHDM-HSD / VHDM-L 6 Row Dcar	d Tri-brid
* 75	296		VHDM-HSD / VHDM-L 6 Row Daughtercard	Hybrid
* 75	190		VHDM / VHDM-L 6 Row Daughtercard Hybr	id
* 75	189		VHDM L-Series 6 Row Daughtercard Assem	ibly
* 74	686		VHDM / VHDM-HSD 8 Row Daughtercard H	lybrid
* 74	680		VHDM-HSD 8 Row Daughtercard Assembly	.,
* 74	886		VHDM / VHDM-HSD 6 Row Daughtercard H	lvbrid
* 74	880		VHDM-HSD 6 Row Daughtercard Assembly	,
* 74	670		VHDM-HSD 5 Row Daughtercard Assembly	,
74) * 74)	030		VHDM 8 Row Daughtercard Assembly	
* 7/	030		VHDM 6 Row Daughtercard Assembly	
* 74	029		VHDM / VHDM-HSD 5 Row, 6 Row, and 8 F Backplane Power Module	₹ow
75	101, 10100, 1010			
ני 75 *	197 75195,7519 197 75198 7519	9	VHDM I -Series 8 Row Backplane Signal Mc	ndule
* 75	049,74000,7400 107 75105 7510	01, 74000, 7400% 16	ערטוירסט ס גטע שמנגנומווי אין אוואטעט א איז א איז א איז איז איז איז איז איז א	it Indule
* 74	919,14980,1498 610 71650 7165	1, 14903, 1498 1 7/659 7/650		
^ /4 * 74	095, 14096, 1469 070 74090 7409	1, 74701, 74702		e
* 74	457, 74458			
* 74	060, 74061, 7406	2, 74075, 74078	8, VHDM 8 Row Backplane Signal Module	
74	077, 74335, 7433	36		
* 74	057, 74058, 7405	9, 74073, 74074	4, VHDM 6 Row Backplane Signal Module	

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 CHECKED BY:
 APPROVED BY:

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 NEWKIRK
 BIXLER



The VHDM, VHDM-HSD, and VHDM L-Series backplane interconnect systems consist of 5, 6, and 8 row modular configurations with custom signal, power and guidance modules. These connectors are two-piece devices, which connect two printed circuit boards. The right angle and vertical receptacle connectors (daughtercard) and header pin connectors (backplane) are through hole devices with eye-of-the-needle compliant pin terminals.

2.0 **PRODUCT DESCRIPTION**

2.1 PRODUCT NAMES

VHDM, VHDM-HSD, and VHDM L-Series

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

Refer to the appropriate sales drawings for information on dimensions, materials, platings and markings.

2.3 SAFETY AGENCY APPROVALS

UL File Number:	E29179
CSA File Number:	152514 (LR19980)

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

Refer to the appropriate sales drawings and other sections of this specification for the necessary referenced documents and specifications.

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4.0 RATINGS

4.1 CURRENT

Signal Contact:1 AmpShield Contact (VHDM-HSD 5 Row):1 AmpShield Contact (VHDM-HSD 6/8 Row):2 AmpsShield Contact (VHDM 6 Row):2 AmpsShield Contact (VHDM 8 row):3 AmpsPower Contact:10 Amps per blade

4.2 SIGNAL CONTACT MATED BULK RESISTANCE (MEASURED VALUES (mOhms))

	6 Row VHDM and L-Series	8 Row VHDM and L-Series	5 Row VHDM- HSD	6 Row VHDM- HSD	8 Row VHDM- HSD	8 Row VHDM Stacker, 18mm Stack Height
A Row	5.8	6.9	6.7	5.3	7.8	7.0
B Row	5.7	7.5	7.3	6.1	8.3	7.0
C Row	7.9	8.4				7.0
D Row	8.5	9.9	9.5	8.8	11.3	7.0
E Row	9.8	10.4	10.3	9.2	11.5	7.0
F Row	10.8	11.8				7.0
G Row		12.9			15.2	7.0
H Row		14.0			15.5	7.0

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5.0 PERFORMANCE

5.1 ELECTRICAL PERFORMANCE

ITEM	TEST CONDITION	REQUIREMENT
CONTACT RESISTANCE (LOW LEVEL)	Mated, 100mA max, 20mV per EIA-364-TP-23	10 milliohm maximum change
INSULATION RESISTANCE	Unmated, 500VDC per EIA-364-TP-21	10,000 megaohms minimum
DIELECTRIC WITHSTANDING VOLTAGE	Unmated, 750VAC per EIA-364-TP-20	No breakdown or flashover
SIGNAL CONTINUITY	Mated per EIA-364-TP-87	No interrupts greater than 10 nanoseconds
COMPLIANT PIN INTERFACE RESISTANCE	Contact inserted into PCB per EIA-364-TP-23	1 milliohm maximum
POWER BLADE CONTACT RESISTANCE	Mated, 10A per EIA-364-TP-06	3 milliohms maximum





5.2 MECHANICAL PERFORMANCE

	ITEM	TEST CONDITIO	ON REQ	UIREMENT	
	SIGNAL WAFER MATING FORCE	Mate daughtercard backplane assen per EIA-364-TP-	40g p 1 and 25g per 1bly (nom 13 (refer to ch maximum	per signal pin shield chevron ninal values) nart on sheet 7 for expected values)	
	POWER BLADE MATING FORCE	Mate daughtercarc backplane assen per EIA-364-TP-	d and 150 hbly (non	g per blade ninal value)	
	DURABILITY	200 Cycles, mated and unma per EIA-364-TP-	ted 10 m 09 char	nilliohm max nge in LLCR	
	VIBRATION	Mated, 10-100⊦ 10g's, 24 hr, 3 a per EIA-364-TP-	lz, 10 m xis char 28	nilliohm max nge in LLCR	
	MECHANICAL SHOCK	Mated, 30g half-s 11ms, 3 axis per EIA-364-TP-	ine, 10 m 27 char	nilliohm max nge in LLCR	
	NORMAL FORCE	Apply perpendicular to terminal at rate 25+/-6mm per min	pendicular force inal at rate of nm per minute		
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TOTAL CONNECTOR MATING FORCE PER PIN

(maximum expected values, standard mate shields)

Product Type	Backplane Pin Length				
Floader Type	6.25 mm	5.15 mm	4.75 mm	4.25 mm	
VHDM 6 Row	85g	100g	100g	100g	
VHDM 8 Row	85g	100g	100g	100g	
VHDM-HSD 5 Row	85g	100g	100g	100g	
VHDM-HSD 6 Row	85g	100g	100g	100g	
VHDM-HSD 8 Row	85g	100g	100g	100g	
VHDM L-Series 6 Row	85g	85g	85g	85g	
VHDM L-Series 8 Row	85g	85g	85g	85g	

Note: The values contained in the chart above represent the maximum expected peak mating force for the entire connector normalized to a per pin value. This force value includes all of the typical elements of total connector mating: signal engagement, shield engagement, and plastic engagement. As shown, the 6.25mm pin provides for the lowest total mating force due to the fact that its peak force occurs prior to the engagement of the shield.

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5.3 ENVIRONMENTAL PERFORMANCE

ITEM	TEST CONDITION	REQUIREMENT
THERMAL SHOCK	Mated, 5 cycles from -55°C to 85°C per EIA-364-TP-32	10 milliohm max change in LLCR
TEMPERATURE LIFE	Mated, +105°C for 1000 hours per EIA-364-TP-17	10 milliohm max change in LLCR
HUMIDITY	Mated, 600 hours from +25°C to +65°C per EIA-364-TP-31	10 milliohm max change in LLCR
DUST	Unmated per EIA-364-TP-50	10 milliohm max change in LLCR
MIXED FLOWING GAS	10 days unmated, 10 days mated, per EIA-364-TP-65 and ASTM B827	10 milliohm max change in LLCR

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5.4 COMPLIANT PIN PERFORMANCE

5.4.1 Insertion Force for Various Plating Types (Typical)

COMPONENT	TIN /	LEAD	BARE Cu / OSP		
	Typical	Maximum	Typical	Maximum	
VHDM / VHDM-HSD Backplane Pin (single pin)	8 lbs	10 lbs	8 lbs	10 lbs	
VHDM / VHDM-HSD Backplane Shield (single pin)	4 lbs	6 lbs	4 lbs	8 lbs	
VHDM / VHDM-HSD Daughtercard Signal (single pin)	4 lbs	6 lbs	4 lbs	8 lbs	
VHDM Daughtercard Shield (single pin)	3 lbs	4 lbs	3 lbs	6 lbs	
VHDM-HSD Daughtercard Shield (single pin)	4 lbs	6 lbs	4 lbs	8 lbs	
Backplane/Daughtercard Power (single contact with 4 pins)	38 lbs	75 lbs	38 lbs	75 lbs	

Note: "Maximum" columns reflect maximum expected values for insertion forces when tested in plated through holes drilled and plated as described in Section 5.4.3. Plating surface finish and PCB materials will impact actual values.

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5.4.2 Retention Force for Various Plating Types (Typical)

COMPONENT	TIN / LEAD		BARE Cu / OSP	
	Typical	Minimum	Typical	Minimum
VHDM / VHDM-HSD Backplane Pin (single pin)	5.5 lbs	4 lbs	5 lbs	4 lbs
VHDM Backplane Shield (single pin)	3 lbs	1 lb	2 lbs	1 lb
VHDM-HSD Backplane Shield (single pin)	2.5 lbs	1.5 lbs	2 lbs	1.5 lbs
VHDM / VHDM-HSD Daughtercard Signal (single pin)	2.5 lbs	1.5 lbs	2 lbs	1.5 lbs
VHDM Daughtercard Shield (single pin)	2 lbs	1 lb	1.5 lbs	1 lb
VHDM-HSD Daughtercard Shield (single pin)	2.5 lbs	1.5 lbs	2 lbs	1.5 lbs
Backplane/Daughtercard Power (single contact with 4 pins)	25 lbs	10 lbs	22 lbs	10 lbs

Note: "Minimum" columns reflect minimum expected values for retention forces when tested in plated through holes drilled and plated as described in Section 5.4.3. Plating surface finish and PCB materials will impact actual values.

Radial hole deformation: 1.5 mils max

Axial hole deformation: 1.0 mil max

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5.4.3 Printed Circuit Board Specifications

Recommended Backplane PCB Thickness:1.8mm minimumRecommended Daughtercard PCB Thickness:1.8mm minimumSignal/Shield Primary Drilled Hole Size:0.66 mm (#71 Drill)Power Primary Drilled Hole Size:0.838 mm (#66 Drill)







PRODUCT SPECIFICATION

6.0 **TEST SEQUENCE**

Bellcore Test Plan

SAMPLE PREPARATION

	GROUP 1	GROUP 2	GROUP 3	GROUP 4		
	Separation Force	 Mating/Unmating	Separation Force	LLCR	-	
		Force	 Məting/Unmating	 Durability		
	 Mating/Unmating			(99 cycles)	
	Force	Thermal Shock		Mating/Unma Force	ting	
	(99 cycles)	(99 cycles)		l Mixed Flowi: Gas (Unmate	ng ed)	
			Mating/Unmating Force	LLCR:		
	l Dust I	l Dust	Separation Force	5th Day 10th Day		
			Compliant Retention Force	 Mixed Flowi:	ng	
	Vibration	Humidity		Gas (Mated)	
	LLCR: X Axis			LLCR: 15th Day 20th Day		
	Y Axis Z Axis	Mating/Unmating Force		Bisturbano	e	
	Shock	 Compliant			-	
	l LLCR: N. Ania	Retention Force		Durability		
	Y Axis Y Axis Z Axis			(98 cycles)	
	 Mating/Unmeting			LLCR		
	Force			Compliant Retention Fo	rce	
	Separation Force					
	Compliant Retention Force					
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